application Serial No.



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UTILITY PATENT	Attorney Docket No.	3029-152			
APPLICATION TRANSMITTAL (Only for new nonprovisional	First Named Inventor	Daniel K. Doe, et al. EL 905056791 US 3			
	Express Mail Label No.				
applications under 37 CFR 1.53(b))	Total Pages				
BY EXPRESS MAIL – Label No. <u>E</u>	T. 905056791 US				
Assistant Commissioner for Patents Box Patent Application Washington, DC 20231					
Sir:					
Enclosed herewith for filing is entitled "Two-Part Structural Adhesivincludes:	s a patent application of Dave Systems and Laminates	aniel K. Doe and Donald E. Gosiewski Incorporating The Same" which			
[X] Specification	[X] Total Page	s 32			
[X] Claims	[X] Total Page	s 5			
[X] Abstract	[X] Total Page	s 1			
[X] Drawing(s) _Formal _X_informal	[X] Total Shee	ts 1			
[X] Combined Declaration and Powe[X] Newly executed (origina[] Copy from a prior applicatesurcharge for late filing)	1 or copy)	Total Pages ional only – must be filed to avoid			
If a continuing application, check ap [] Continuation [] Divi	sional				
[] Amend the specification by insert "This is a [] continuation	ing, before the first line, th	ne following sentence: continuation-in-part of copending			

filed

Attorney Docket No. 3029-152

2.4. • • • • • • • • • • • • • • • • • • •
 [X] An Assignment of the invention to [] is attached. A separate cover sheet in compliance with 37 CFR 3.28 and 3.11 is included [X] will follow. [] has been filed in the prior application
[] Small Entity Status is hereby claimed
[] Information Disclosure Statement (IDS) PTO-1449 [] Copies of IDS Citations
[X] Request and Certification for Non-publication under 35 U.S.C. 122(b)(2)(B)(i) ENCLOSED .
[] Request to Rescind previous Non-publication Request under 35 U.S.C. 122(b)(2)(B)(ii) ENCLOSED .
[] Request for Redacted Publication under 35 U.S.C. 122(b)(2)(B)(v) and the Redacted Publication ENCLOSED.
[] Request for Early Publication under 35 U.S.C. 122(b)(1)(A) ENCLOSED.
[] Preliminary Amendment
[X] Return Receipt Postcard
[] Other: .
[] Cancel in this application original claims of the prior application before calculating the filing fe

The Fee has	s been calculated	as shown below:
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			. ,		Small Entity				Other than a small entity			
FOR	(Col. 1) No. Filed		(Col. No. 1	. 2) Extra	Rate	Fe	e	OR	Rate		Fee	
Basic Fee							370.00			**	740.00	
Total Claims	35	- 20	= 15	_X	9	=	.00	X	18	= =	270.00	
Ind. Claims	5	- 3	= 2	X	42	=	.00	X	84	·- ·- ·- ·	168.00	
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			*	TOTAL	H HP= =-		.00				1,178.00	

^{*} If the difference in Col. 1 is less than zero, enter "0" in Col. 2.

Fee paymen	t being	made:
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[X] I	Enclosed					
	[X] Basic Filing Fee			1,178.00	•	
	[] Recording Assignment: 37 CFR 1.21(h)	\$.00		
	[] Publication Fees	\$		0.00		
			Total Fees Enclosed:	1,178.00	••	
Prior	to cover filing fee and assignment	gnment reco	ordation fee is eliciosed.			
	Priority of application C	ountry	, Appln No.	, filed		•
[]	Certified Copy of Priori	y Documen	nt Country , Appl	n. No.	, Filed	
	[] is/are attached []	will follow	[] has been filed in the par	ent applica	tion S/N	•
[X]	37 CFR 1.16, 1.17 and 1	.21(h) asso	ized to charge payment of a ciated with this communica o copies of this sheet are en	tion or cred	al filing fees it any overpa	required u yment to

Pitney, Hardin, Kipp & Szuch, LLP

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Attorneys For Applicants

Enclosure

U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number

REQUEST AND CERTIFICATION
UNDER
35 U.S.C. 122(b)(2)(B)(i)

First Named Inventor Daniel K. Doe, et al.

Title Two-Part Structural Adhesive Systems and Laminates Incorporating the Same

Atty Docket Number 3029-152

I hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).

February 7, 2002

Date

Lindsay S. Adams

Typed or printed name

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing.**

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**

ACOMESE CENTON

Burden Hour Statement. This collection of information is required by 37 CFR 1 213(a). The information is used by the public to request that an application not be published under 35 U.S.C. 122(b) (and the PTO to process that request). Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1 14. This form is to take 6 minutes to complete. This time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231 DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO. Assistant Commissioner for Patents, Washington, DC 20231.